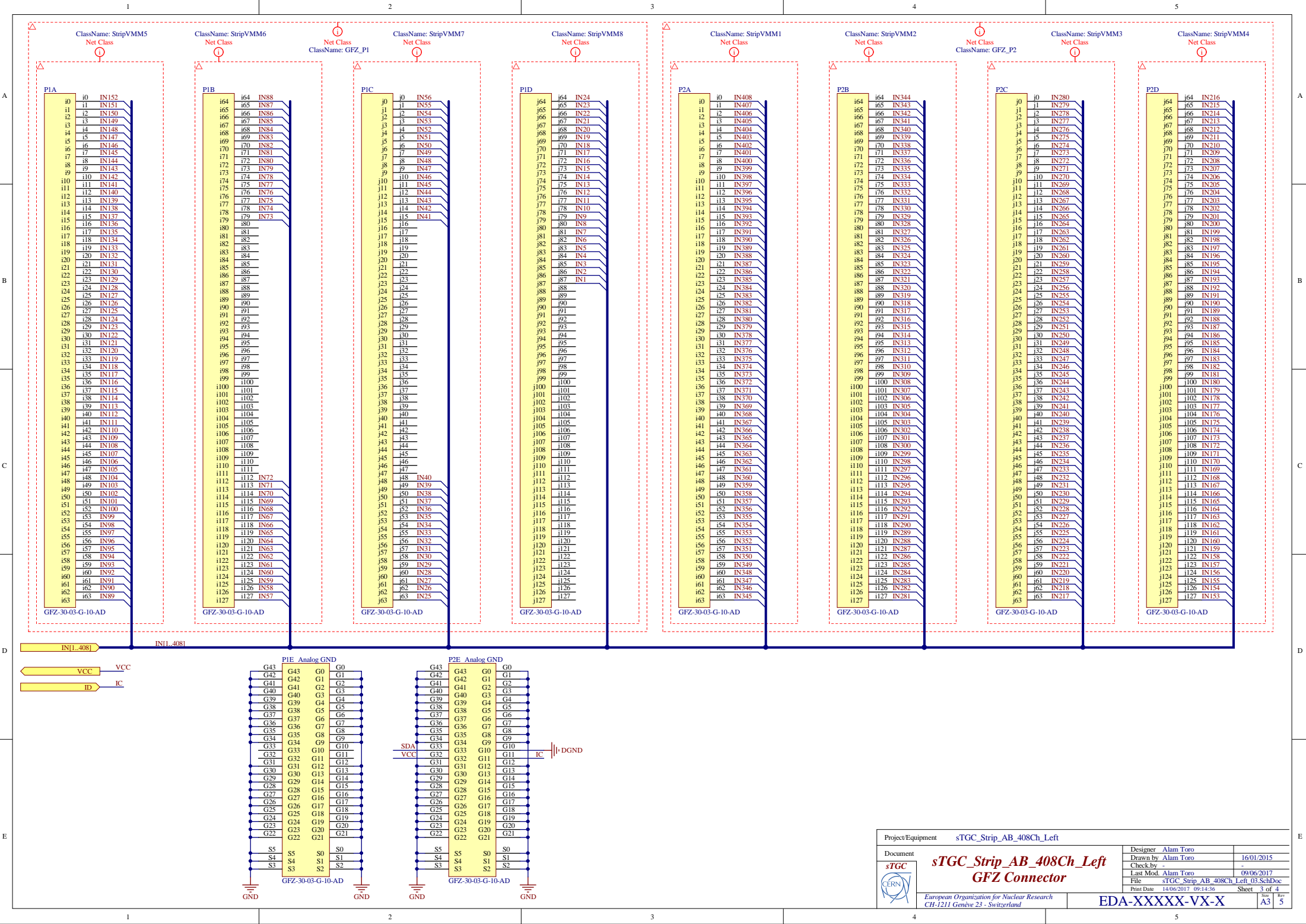
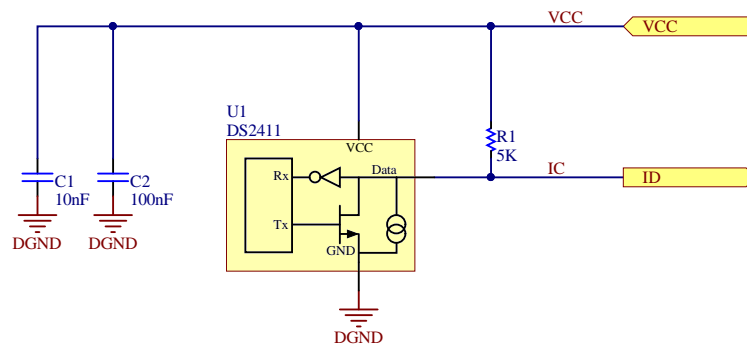


5.0	Screw holes grounded	14/06/2017
4.0	Requirements from USTC presented in last Muon Week for all Strip Adapter Boards	25/01/2016
3.0	Notch at left side added to other chambers VMM's Load balancing scheme in Inner chambers. Notch at left side added to other chambers.	28/10/2015
2.0	Via sizes changed to 0,454mm (outher radius) and 0,254mm (hole). Thickness of tracks changed to 0.15mm. Overall thickness also changed in order to maintain characteristic impedance of tracks	19/08/2015
1.0	Release for Production	05/12/2016
Rev	Description	Date
Project/Equipment sTGC_Strip_AB_408Ch_Left		
<div>Document</div> <div><div>sTGC</div><div>CERN</div></div>	Designer Alam Toro	
	Drawn by Alam Toro	16/01/2015
	Check.by -	-
	Last Mod. Alam Toro	09/06/2017
	File sTGC_Strip_AB_408Ch_Left_01.SchDoc	
	Print Date 14/06/2017 09:14:36	Sheet 1 of 4
European Organization for Nuclear Research CH-1211 Genève 23 - Switzerland		EDA-XXXXXX-VX-X <div>Size A4</div> <div>Rev 5</div>



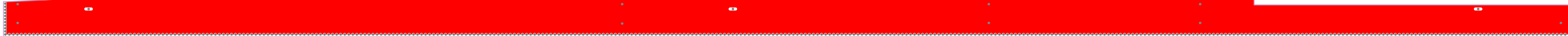
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		Drawn by	Alam Toro
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		Last Mod.	Alam Toro
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		A4	5



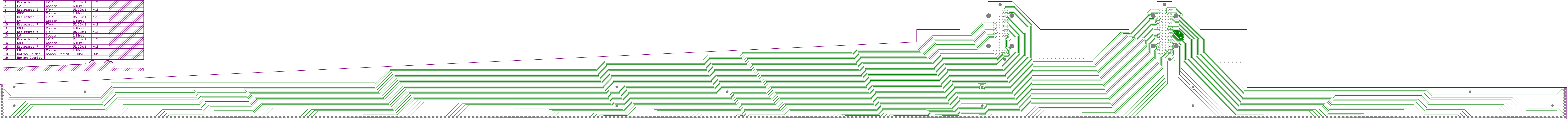


Project/Equipment sTGC_Strip_AB_408Ch_Left			Designer Alam Toro		
<div>Document</div> <div><div>sTGC</div><div>CERN</div></div> <div><i>sTGC_Strip_AB_408Ch_Left</i> <i>Identification Chip</i></div> <div>European Organization for Nuclear Research CH-1211 Genève 23 - Switzerland</div>			Drawn by Alam Toro	16/01/2015	
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			Print Date 14/06/2017 09:14:37	Sheet 4 of 4	
EDA-XXXXXX-VX-X			Size A4	Rev 5	

Layer	Name	Material	Thickness	Constant	Board Layer	Stack
1	Top Overlay					
2	Top Solder	Solder Resist	0.40mil	3.5		
3	L1	Copper	1.18mil			
4	Dielectric 1	FR-4	15.00mil	4.2		
5	L2	Copper	1.18mil			
6	Dielectric 2	FR-4	15.00mil	4.2		
7	GN3	Copper	1.18mil			
8	Dielectric 3	FR-4	15.00mil	4.2		
9	L4	Copper	1.18mil			
10	Dielectric 4	FR-4	15.00mil	4.2		
11	GN5	Copper	1.18mil			
12	Dielectric 5	FR-4	15.00mil	4.2		
13	L6	Copper	1.18mil			
14	Dielectric 6	FR-4	15.00mil	4.2		
15	GN7	Copper	1.18mil			
16	Dielectric 7	FR-4	15.00mil	4.2		
17	L8	Copper	1.18mil			
18	Bottom Solder	Solder Resist	0.40mil	3.5		
19	Bottom Overlay					



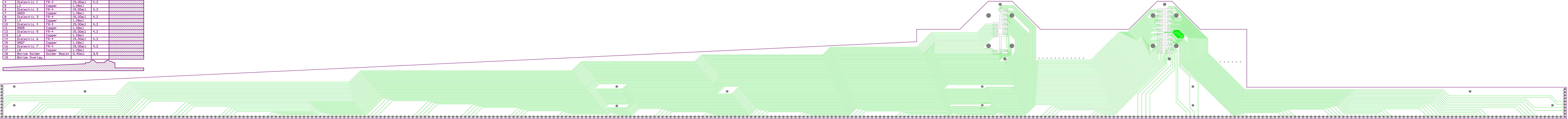
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	L1	Copper	1.18mil		
4	Dielectric 1	FR-4	15.00mil	4.2	
5	L2	Copper	1.18mil		
6	Dielectric 2	FR-4	15.00mil	4.2	
7	GND3	Copper	1.18mil		
8	Dielectric 3	FR-4	15.00mil	4.2	
9	L4	Copper	1.18mil		
10	Dielectric 4	FR-4	15.00mil	4.2	
11	GND5	Copper	1.18mil		
12	Dielectric 5	FR-4	15.00mil	4.2	
13	L6	Copper	1.18mil		
14	Dielectric 6	FR-4	15.00mil	4.2	
15	GND7	Copper	1.18mil		
16	Dielectric 7	FR-4	15.00mil	4.2	
17	L8	Copper	1.18mil		
18	Bottom Solder	Solder Resist	0.40mil	3.5	
19	Bottom Overlay				



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	L1	Copper	1.18mil		
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6	Dielectric 2	FR-4	15.00mil	4.2	
7	GND3	Copper	1.18mil		
8	Dielectric 3	FR-4	15.00mil	4.2	
9	L4	Copper	1.18mil		
10	Dielectric 4	FR-4	15.00mil	4.2	
11	GND5	Copper	1.18mil		
12	Dielectric 5	FR-4	15.00mil	4.2	
13	L6	Copper	1.18mil		
14	Dielectric 6	FR-4	15.00mil	4.2	
15	GND7	Copper	1.18mil		
16	Dielectric 7	FR-4	15.00mil	4.2	
17	L8	Copper	1.18mil		
18	Bottom Solder	Solder Resist	0.40mil	3.5	
19	Bottom Overlay				



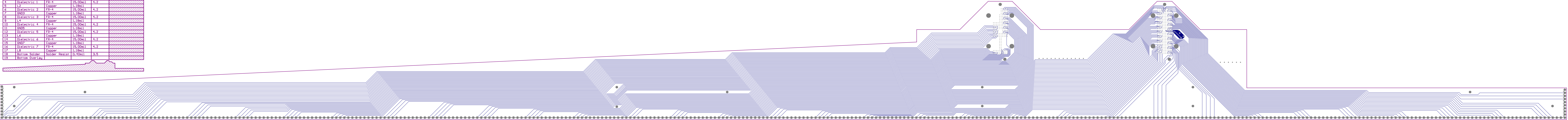
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				[Hatched Pattern]
2	Top Solder	Solder Resist	0.40mil	3.5	
3	L1	Copper	1.18mil		
4	Dielectric 1	FR-4	15.00mil	4.2	
5	L2	Copper	1.18mil		
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12	Dielectric 5	FR-4	15.00mil	4.2	
13	L6	Copper	1.18mil		
14	Dielectric 6	FR-4	15.00mil	4.2	
15	GND7	Copper	1.18mil		
16	Dielectric 7	FR-4	15.00mil	4.2	
17	L8	Copper	1.18mil		
18	Bottom Solder	Solder Resist	0.40mil	3.5	
19	Bottom Overlay				



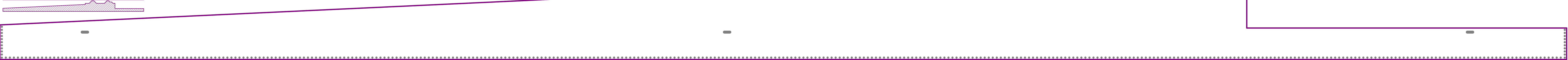
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	L1	Copper	1.18mil		
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17	L8	Copper	1.18mil		
18	Bottom Solder	Solder Resist	0.40mil	3.5	
19	Bottom Overlay				



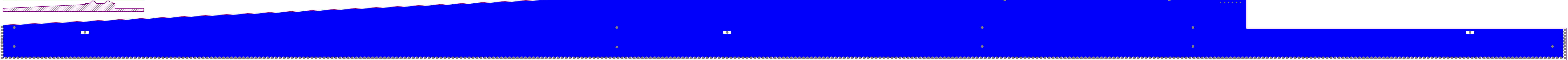
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	L1	Copper	1.18mil		
4	Dielectric 1	FR-4	15.00mil	4.2	
5	L2	Copper	1.18mil		
6	Dielectric 2	FR-4	15.00mil	4.2	
7	GND3	Copper	1.18mil		
8	Dielectric 3	FR-4	15.00mil	4.2	
9	L4	Copper	1.18mil		
10	Dielectric 4	FR-4	15.00mil	4.2	
11	GND5	Copper	1.18mil		
12	Dielectric 5	FR-4	15.00mil	4.2	
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17	L8	Copper	1.18mil		
18	Bottom Solder	Solder Resist	0.40mil	3.5	
19	Bottom Overlay				



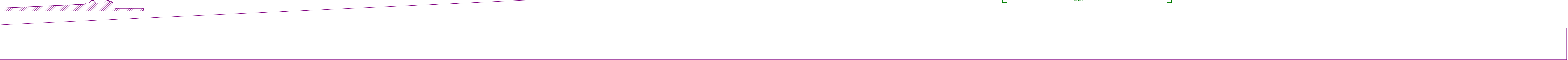
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	L1	Copper	1.18mil		
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12	Dielectric 5	FR-4	15.00mil	4.2	
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15	GND7	Copper	1.18mil		
16	Dielectric 7	FR-4	15.00mil	4.2	
17	L8	Copper	1.18mil		
18	Bottom Solder	Solder Resist	0.40mil	3.5	
19	Bottom Overlay				



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				[Hatched]
2	Top Solder	Solder Resist	0.40mil	3.5	
3	L1	Copper	1.18mil		[Hatched]
4	Dielectric 1	FR-4	15.00mil	4.2	
5	L2	Copper	1.18mil		[Hatched]
6	Dielectric 2	FR-4	15.00mil	4.2	
7	GND3	Copper	1.18mil		[Hatched]
8	Dielectric 3	FR-4	15.00mil	4.2	
9	L4	Copper	1.18mil		[Hatched]
10	Dielectric 4	FR-4	15.00mil	4.2	
11	GND5	Copper	1.18mil		[Hatched]
12	Dielectric 5	FR-4	15.00mil	4.2	
13	L6	Copper	1.18mil		[Hatched]
14	Dielectric 6	FR-4	15.00mil	4.2	
15	GND7	Copper	1.18mil		[Hatched]
16	Dielectric 7	FR-4	15.00mil	4.2	
17	L8	Copper	1.18mil		[Hatched]
18	Bottom Solder	Solder Resist	0.40mil	3.5	
19	Bottom Overlay				[Hatched]



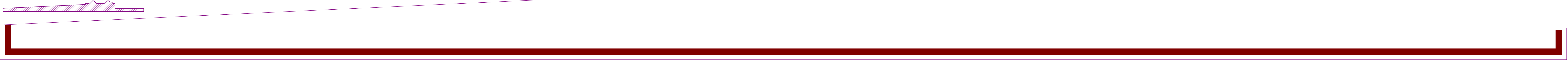
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				[Hatched]
2	Top Solder	Solder Resist	0.40mil	3.5	
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6	Dielectric 2	FR-4	15.00mil	4.2	
7	GND3	Copper	1.18mil		[Hatched]
8	Dielectric 3	FR-4	15.00mil	4.2	
9	L4	Copper	1.18mil		[Hatched]
10	Dielectric 4	FR-4	15.00mil	4.2	
11	GND5	Copper	1.18mil		[Hatched]
12	Dielectric 5	FR-4	15.00mil	4.2	
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14	Dielectric 6	FR-4	15.00mil	4.2	
15	GND7	Copper	1.18mil		[Hatched]
16	Dielectric 7	FR-4	15.00mil	4.2	
17	L8	Copper	1.18mil		[Hatched]
18	Bottom Solder	Solder Resist	0.40mil	3.5	
19	Bottom Overlay				[Hatched]



Layer	Name	Material	Thickness	Constant	Board Layer Stack
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17	L8	Copper	1.18mil		
18	Bottom Solder	Solder Resist	0.40mil	3.5	
19	Bottom Overlay				



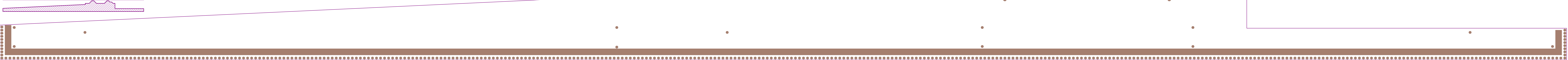
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
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15	GND7	Copper	1.18mil		
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17	L8	Copper	1.18mil		
18	Bottom Solder	Solder Resist	0.40mil	3.5	
19	Bottom Overlay				



Layer	Name	Material	Thickness	Constant	Board Layer Stack
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3	L1	Copper	1.18mil		
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17	L8	Copper	1.18mil		
18	Bottom Solder	Solder Resist	0.40mil	3.5	
19	Bottom Overlay				



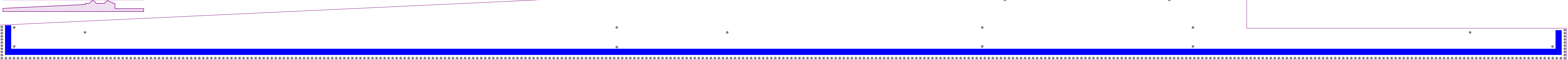
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				[Hatched pattern]
2	Top Solder	Solder Resist	0.40mil	3.5	
3	L1	Copper	1.18mil		
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19	Bottom Overlay				



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16	Dielectric 7	FR-4	15.00mil	4.2	
17	L8	Copper	1.18mil		
18	Bottom Solder	Solder Resist	0.40mil	3.5	
19	Bottom Overlay				



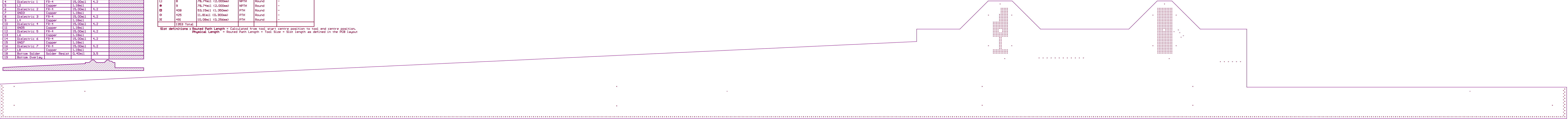
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				[Hatched pattern]
2	Top Solder	Solder Resist	0.40mil	3.5	
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16	Dielectric 7	FR-4	15.00mil	4.2	
17	L8	Copper	1.18mil		
18	Bottom Solder	Solder Resist	0.40mil	3.5	
19	Bottom Overlay				

Symbol	Hit Count	Finished Hole Size	Plated	Hole Type	Physical Length
⊙	1	78.74mil (2.000mm)	PTH	Slot	253.43mil (6.437mm)
◇	2	78.74mil (2.000mm)	NPTH	Slot	253.43mil (6.437mm)
▽	4	65.00mil (1.651mm)	NPTH	Round	-
○	5	15.75mil (0.400mm)	PTH	Round	-
□	8	78.74mil (2.000mm)	NPTH	Round	-
✱	9	78.74mil (2.000mm)	NPTH	Round	-
⊠	408	53.15mil (1.350mm)	PTH	Round	-
⊛	425	11.81mil (0.300mm)	PTH	Round	-
⊞	491	10.08mil (0.256mm)	PTH	Round	-
	1353 Total				

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Physical Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				[Hatched pattern]
2	Top Solder	Solder Resist	0.40mil	3.5	
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